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**Miller**

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(54) **POLYAMIDE ADHESIVE AND ARTICLES INCLUDING THE SAME**

(75) Inventor: **Richard A. Miller**, Kingsport, TN (US)

(73) Assignee: **H.B. Licensing & Financing, Inc.**, St. Paul, MN (US)

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(52) **U.S. Cl.** ..... **428/474.4**; 428/477.7; 428/458; 525/178

(58) **Field of Classification Search** ..... 428/474.4, 428/477.7, 458; 525/178

See application file for complete search history.

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*Primary Examiner*—James Seidleck  
*Assistant Examiner*—Saira Haider

(57) **ABSTRACT**

A hot melt adhesive composition that includes thermoplastic polyamide, adhesion promoter that includes at least one acid group, and wax having a melting point greater than 82° C.

**30 Claims, No Drawings**